LGA Low Inductance Capacitors, KGA Series

0204/0306 Land Grid Array





Land Grid Array (LGA) capacitors are the latest family of low inductance MLCCs from KYOCERA AVX. These new LGA products are the third low inductance family developed by KYOCERA AVX. The innovative LGA technology sets a new standard for low inductance MLCC performance.

Our initial 2 terminal versions of LGA technology deliver the performance of an 8 terminal IDC low inductance MLCC with a number of advantages including:

Simplified layout of 2 large solder pads compared to 8 small pads for IDCs

Opportunity to reduce PCB or substrate contribution to system ESL by using multiple parallel vias in solder pads Advanced FCT manufacturing process used to create uniformly flat terminations on the capacitor that resist "tombstoning"

Better solder joint reliability

APPLICATIONS

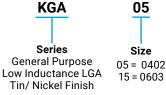
Semiconductor Packages

- Microprocessors/CPUs
- Graphics Processors/GPUs
- Chipsets
- **FPGAs**
- **ASICs**

Board Level Device Decoupling

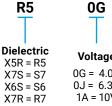
- Frequencies of 300 MHz or more
- ICs drawing 15W or more
- Low voltages
- · High speed buses

HOW TO ORDER









0G Voltage 0G = 4.0V0J = 6.3V1A = 10V



103





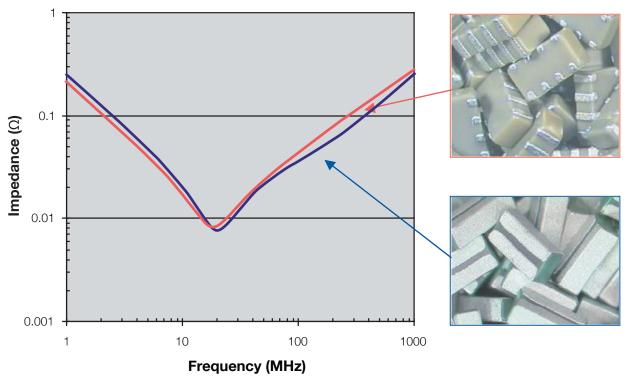




PACKAGING CODES

Code	EIA (inch)	IEC(mm)	7" Paper	7" Embossed	13" Paper	13"Embossed
05	0402	1005	Н		N	
15	0603	1608		U		L

0306 2 TERMINAL LGA COMPARISON WITH 0306 8 TERMINAL IDC



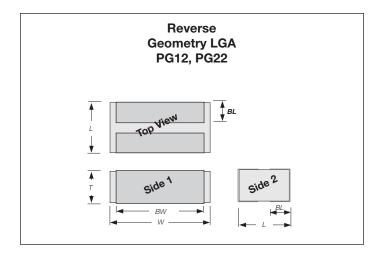
LGA Low Inductance Capacitors, KGA Series



Capacitance Range

SIZE LG12 (05)					LG22 (15)											
Length	mm (in.)	0.50 (0.020)				0.76 (0.030)										
Width	mm (in.)	1.00 (0.039)				1.60 (0.063)										
Temp. Char.		X5R (R5) X7S (S7)		X6S (S6)		X7R (R7)		X5R (R5)		X7S (S7)		X6S (S6)				
Working \	/oltage	6.3	4	6.3	4	6.3	4	10	6.3	4	6.3	4	6.3	4	6.3	4
		(0J)	(0G)	(0J)	(0G)	(0J)	(0G)	(1A)	(0J)	(0G)	(0J)	(0G)	(0J)	(0G)	(0J)	(0G)
Cap (µF)	0.010 (103)	Α	Α	Α	Α	Α	Α	Z	Z	Z	Z	Z	Z	Z	Z	Z
	0.022 (223)	Α	Α	Α	Α	Α	Α				Z	Z	Z	Z	Z	Z
	0.047 (473)	Α	Α	Α	Α	Α	Α				Z	Z	Z	Z	Z	Z
	0.100 (104)	Α	Α	Α	Α	Α	Α				Z	Z	Z	Z	Z	Z
	0.220 (224)										Z	Z		Z		Z
	0.330 (334)											Z		Z		Z
	0.470 (474)											Z		Z		Z
	1.000 (105)															
	2.200 (225)									·						

PAPER Embossed(EMB)



PART DIMENSIONS

MM (INCHES)

	Series	L	L W		BW	BL	
	LG12 (05)	0.5±0.05	1.00±0.10	0.50±0.05	0.80±0.10	0.13±0.08	
		(0.020±0.002)	(0.039±0.004)	(0.020±0.002)	(0.031±0.004)	(0.005±0.003)	
	1.000 (45)	0.76±0.10	1.60±0.10	0.50±0.05	1.50±0.10	0.28±0.08	
	LG22 (15)	(0.030±0.004)	(0.063±0.004)	(0.020±0.002)	(0.059±0.004)	(0.011±0.003)	

RECOMMENDED SOLDER PAD DIMENSIONS

MM (INCHES)



Series	PL	PW1	G		
LG12 (05)	0.50 (0.020)	1.00 (0.039)	0.20 (0.008)		
LG22 (15)	0.65 (0.026)	1.50 (0.059)	0.20 (0.008)		